



NOTE: (UNLESS OTHERWISE SPECIFIED)

1. VERIFY ARTWORK TO SUPPLIED IPC-356 NETLIST.
2. PRINTED CIRCUIT BOARD (PCB) TO BE FABRICATED IN ACCORDANCE WITH IPC-600A, CLASS 2 LATEST REVISION.
3. MATERIAL TO BE FR4 GLASS EPOXY LAMINATE IN ACCORDANCE WITH IPC-4101/24. FR4 170Tg, OR RoHS EQUIVALENT.
4. APPLY SOLDERMASK OVER BARE COPPER IN ACCORDANCE WITH IPC-SM-840, LATEST REVISION, BOTH SIDES, LIQUID-PHOTO IMAGEABLE (LPI) COLOR GREEN.
5. SILKSCREEN ACCORDING TO SUPPLIED ARTWORK USING PERMANENT, WHITE, NON-CONDUCTIVE, EPOXY BASED INK. LANDS AND EXPOSED PLATED AREAS TO BE FREE OF INK.
6. FINISH: ENIG (ELECTROLESS NICKEL IMMERSION GOLD)
7. MARK ALL BOARDS WITH EITHER, CAGE CODE, DATE CODE, AND/OR UL RATING ON SOLDER SIDE USING SILKSCREEN OR ETCH.
8. BOARDS TO BE 100% TESTED FOR CONTINUITY AND ISOLATION.
9. PLATED THROUGH HOLE DIMENSIONS APPLY AFTER PLATING, FISINISHED HOLE SIZE (FHS).
10. ALL PLATED THROUGH HOLES TO HAVE MINIMUM OF 0.001" PLATED COPPER.
11. ALL HOLES TO BE LOCATED WITHIN 0.003" DIAMETER FROM TRUE POSITION; LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".
12. CONDUCTOR WIDTHS AND SPACING SHALL BE BETWEEN +/- 20% OF SUPPLIED ARTWORK.
13. MAXIMUM BOW AND TWIST NOT TO EXCEED 0.0075" PER INCH.
14. BOARDS TO MEET THE REQUIREMENTS OF UL796 WITH A FLAMMABILITY RATING OF 94V-0 OR BETTER.
15. FINISHED BOARD THICKNESS IS INDICATED IN THE PCB CROSS-SECTIONAL DIAGRAM.
16. COPPER WEIGHTS SHOWN IN PCB CROSS-SECTIONAL DIAGRAM INDICATE WEIGHTS AFTER PLATING.
17. VENDOR MAY NOT MODIFY MASTER GERBER DATA WITHOUT AUTHORIZATION, EXCEPT BELOW:
 - A. NON-FUNCTIONAL PADS MAY BE REMOVED FROM INTERNAL SIGNAL LAYERS AS NEEDED.
 - B. TEARDROPS/PAD FILLETS MAY BE ADDED AS NEEDED TO MAINTAIN ANNULAR RING AT THE CONDUCTOR-TO-PAD CONNECTION POINT.
18. ASSEMBLY PROCESS IS RoHS, BASE LAMINATE MUST BE RoHS COMPLIANT.
19. DIFF PAIRS: 90 OHM DIFF PAIRS +/- 10% ON LAYERS 1 & 4 WITH .127mm ETCH, 0.127mm SPACING.

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Silk Screen			Legend	GTO
Surface Material	Top Solder Mask	0.0232mm	SM-003	Solder Mask	GTS
CF-003	Top Layer	0.0180mm		Signal	GTL
Prepreg		0.1104mm	PP-023	Dielectric	
CF-003	Layer 2	0.0350mm		Signal	G1
Prepreg		1.2000mm	PP-023	Dielectric	
CF-003	Layer 3	0.0350mm		Signal	G2
Prepreg		0.1104mm	PP-023	Dielectric	
CF-003	Bottom Layer	0.0180mm		Signal	GBL
Surface Material	Bottom Solder Mask	0.0232mm	SM-003	Solder Mask	GBS
	Bottom Silk Screen			Legend	GBO
Total thickness: 1.5732mm					

PCB THICKNESS = 1.575mm / 62 mils.

DIELECTRIC MATERIAL AND THICKNESS TO BE DETERMINED BY FABRICATION HOUSE.

Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
◇	536	0.3048mm	Plated	+0.0762mm/-0.3048mm
☆	12	0.4000mm	Plated	+/-0.0500mm
✧	4	0.6000mm	Plated	+/-0.0500mm
▽	2	0.7500mm	Non-Plated	+/-0.0250mm
⊗	9	0.8890mm	Plated	+/-0.0762mm
⊕	9	0.9906mm	Non-Plated	+/-0.0762mm
○	4	3.0480mm	Non-Plated	+/-0.0762mm
576 Total				

	REV	UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES. TOLERANCES ARE: DECIMALS: .XX +/- .01 .XXX +/- .005 FRACTIONS: +/- 1/64 ANGLES: +/- 1 ° DO NOT SCALE DWG. SCALE 1:1	DRAWN	NET RESULTS	05/16/24	ODIC, INC. 295 FOSTER ST. SUITE 202 LITTLETON, MA 01460			
	ECO		CHECKED			TITLE: GHL NAATOS SAMPLE PREP MAIN BOARD FABRICATION DRAWING			
	DATE		ENGINEER						
	APP			NOTICE ANY DISCLOSURE, REPRODUCTION, OR USE OF THIS DRAWING, OR ANY PART OF THIS DRAWING WITHOUT WRITTEN PERMISSION FROM ODIC, INC. IS STRICTLY PROHIBITED.			SIZE C	PART NO. 263-03-001	DOCUMENT REVISION A